

SPECIFICATION AND PERFORMANCE

| Series 115U-A103 | File | 115U-A103_SPEC_1 | Date | 2021/10/20 | |
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 115U-A103

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

| MATERIALS | | | |
|-----------|-----------|--|--|
| NO. | PART NAME | DESCRIPTION | |
| 1 | HOUSING | LCP, UL94V-0, Black | |
| 2 | SLDER | LCP, UL94V-0, Black | |
| 3 | CONTACT | C5210, G/F on contact & solder area, under plating nickel plating over all | |
| 4 | SHELL | SUS304, solder area: G/F, under plating nickel plating over all | |
| 5 | LINK | SUS304 | |
| 6 | SPRING | SWP-B | |

| RATING | | |
|-----------------------|-----------------|--|
| Rated Voltage | 10 VDC | |
| Rated Current | 0.5 A per pin | |
| Operating Temperature | -40 °C to 85 °C | |
| Durability | 5000 cycles | |

| ELECTRICAL | | | |
|------------------------------------|------------------------------|--|--|
| Item | Requirement | Test Condition | |
| Low Level Contact Resistance | 100 m Ohm Max | Solder connectors to PCB and insert dummy card into shell, measure by applying closed circuit current of 10mA maximum at open circuit voltage of 20mV (max). (EIA-364-23) | |
| Dielectric Withstanding Voltage | No Broken | 500V AC (rms.) between two adjacent for 1 minute. (EIA-364-20) | |
| Insulation Resistance | 1000 M Ω min. initial | Impressed voltage 250V DC for 1 minute. Test between adjacent circuit. (EIA364-21) | |

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| MECHANICAL | | | |
|----------------------|--|--|--|
| Item | Requirement | Test Condition | |
| Card Insertion Force | 10N Max | Operation Speed : 25 mm/min. Measure the | |
| | | force required to mate connector. (EIA-364-13B) | |
| Durability | Max. Change from initial contact resistance $40m\Omega$ max. no physical damage to connector shall occur | Cycle rate: 400 to 600 cycles per hour No. of cycle: 5,000 cycles. (EIA 364-09) | |
| Vibration | No electrical discontinuity greater than 0.1or 1µsec shall occur. | Frequency Range: 10-55-10 Total Amplitude: 1.52 mm p-p or 9.81m/sec^2. Duration: 2 hours tree axes(6 hours in total) (EIA364-28) | |
| Mechanical Shock | No electrical discontinuity greater than 0.1or 1µsec shall occur. | Accelerated Velocity: 50 G (490 m/sec^2) Waveform: Semi Sine Duration: 11 m sec. No of Shocks: 6/dir., 3 axis,(total of 18 Shocks) (EIA364-27) | |

| ENVIRONMENTAL | | | |
|--------------------------|---|---|--|
| Item | Requirement | Test Condition | |
| Thermal Shock | Max. Change from initial contact Resistance 40mΩ Max No physical damage to connector shall occur. | Temperature Range: -55 to 85 $^{\circ}$ C No. of Cycles: 5 cycles for 30 minutes (EIA364-32) | |
| Humidity-Thermal Cycling | Max. Change from initial contact Resistance $40m\Omega$ Max Insulation Resistance: $1000 M\Omega$ Min. initial $100 M\Omega$ Min. after test No physical damage to connector shall occur. | Ambient Temp.: 25 to 65 $^{\circ}$ C Relative humidity: 90 to 95 % Duration: 10 cycles (EIA364-31) | |
| Temperature Life | Max. Change from initial contact Resistance 40mΩ Max No physical damage to connector shall occur. | Chamber Temperature: 85±2 °C Duration: 96 hours (EIA364-17) | |
| Salt Spray Test | Max. Change from initial contact Resistance 40mΩ Max No physical damage to connector shall occur. | Salt Solution: 5±1.0% Length of Test: 12 hours Dummy card engaged during test (EIA364-26) | |

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| SOLDER ABILITY | | | |
|---------------------------------|--|--|--|
| Item | Requirement | Test Condition | |
| Solder ability | Wet Solder Coverage: | Solder Temperature: 245±3℃ | |
| | 95% Min. | Immersion Duration: 5 ± 0.5 sec. (J-STD-002B) | |
| Resistance to soldering heat | No melting, cracks or functional damage allowed | Preheating temperature: 150 ~ 200°C, 60~120 seconds Liquidus temperature (TL): 217°C, 60~150 seconds Peak temperature: 260°C Time within 5 °C of peak temperature (Tc): 255°C, 30seconds | |





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